### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chih-Jen WU	03/12/2009
Chen-Ming HUANG	03/12/2009
An-Chun TU	03/12/2009

### RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12402124

### **CORRESPONDENCE DATA**

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 9727398635

Email: lydia.eppshilliard@haynesboone.com

Correspondent Name: David M. O'Dell

Address Line 1: HAYNES AND BOONE, LLP IP Section

Address Line 2: 2323 Victory Avenue, Suite 700

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.1231
NAME OF SUBMITTER:	David M. O'Dell

PATENT REEL: 022729 FRAME: 0604 40.00 124021

500867980

Total Attachments: 2

source=1231\_Assignment#page1.tif source=1231\_Assignment#page2.tif

PATENT REEL: 022729 FRAME: 0605

Docket No.: 2008-0873 / 24061.1231

Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- (1) Chih-Jen Wu
  of No. 9, Lane 28, Alley 167, Chang-Chun Street Hsin-Chu City, Taiwan, R.O.C.
  (2) Chen-Ming Huang
  of No. 9, Lane 142, Guanghua 2nd Street, North District Hsinchu City 300, Taiwan, R.O.C.
- (3) An-Chun Tu of 3F, No. 5, Lane 26, Sec. 4, Jhongsiao E. Road, Da-an District Taipei City 106, Taiwan, R.O.C.

have invented certain improvements in

# ADVANCED PROCESS CONTROL FOR GATE PROFILE CONTROL

for which we have executed an application for Letters Patent of the United States of America,

	of even date filed herewith; and
X	filed on March 11, 2009 and assigned application number 12/402,124; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

- 1 -

Docket No.: 2008-0873 / 24061.1231

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Chih-Jen Wu
Residence Address:	No. 9, Lane 28, Alley 167, Chang-Chun Street Hsin-Chu City, Taiwan, R.O.C.
Dated: $3/12/09$	Inventor Signature
Inventor Name:	Chen-Ming Huang
Residence Address:	No. 9, Lane 142, Guanghua 2nd Street, North District Hsinchu City 300, Taiwan, R.O.C.
Dated: 3/12/0	Inventor Signature
Inventor Name:	An-Chun Tu
Residence Address:	3F, No. 5, Lane 26, Sec. 4, Jhongsiao E. Road, Da-an District Taipei City 106, Taiwan, R.O.C.
Dated: 3/12 'of	Inventor Signature

-2-

**RECORDED: 05/24/2009** 

0jwub 2009/03/13 \$8:04:15 .